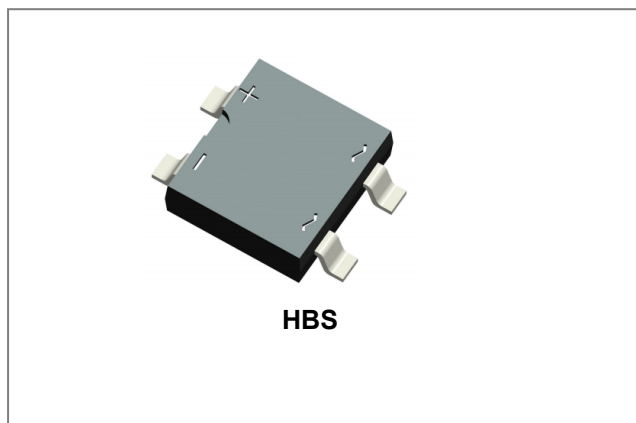


HBS802 THRU HBS810

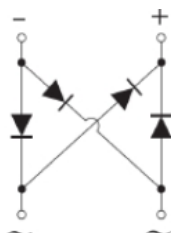
Glass Passivated Single-Phase 8.0Amp Surface Mount Bridge Rectifier



Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High forward current capability up to 8.0A;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: HBS;
- Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed:
Solder Reflow 260°C, 10seconds;
- Polarity: As marked on body;
- Marking: Type number;

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

Type Number	Symbol	HBS802	HBS804	HBS806	HBS808	HBS810	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	140	280	420	560	700	V
Maximum average forward rectified output current at @T _A =25°C	$I_{(AV)}$	8					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	200					A
Rating for fusing (t<8.3ms)	I^2t	166					A ² sec

Electrical Characteristics@T_A=25°C unless otherwise specified

Type Number	Symbol	HBS802	HBS804	HBS806	HBS808	HBS810	Units
Maximum Forward Voltage (per element) @I _F =1A @I _F =4A @I _F =8A	V _F	0.82 Typ. 0.87 Max. 0.89 Typ. 0.94 Max. 0.94 Typ. 1.00 Max.					V
Maximum Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I _R	0.15 Typ. 5.0 Max. 20.0 Typ. 100 Max.					μA
Typical capacitance(Note 1)	Cj	49					pF

* Pulse width < 300 μ s, duty cycle < 2%

Thermal-Mechanical Specifications@T_A=25°C unless otherwise specified

Type Number	Symbol	HBS802	HBS804	HBS806	HBS808	HBS810	Units
Typical Thermal Resistance	R _{θJA} R _{θJC} R _{θJL}	70.0 11.0 14.0					°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150					°C

Note: 1. Mounted at 1.0 MHz and applied reverse voltage of 5.0V DC;

Ratings and Characteristics Curves

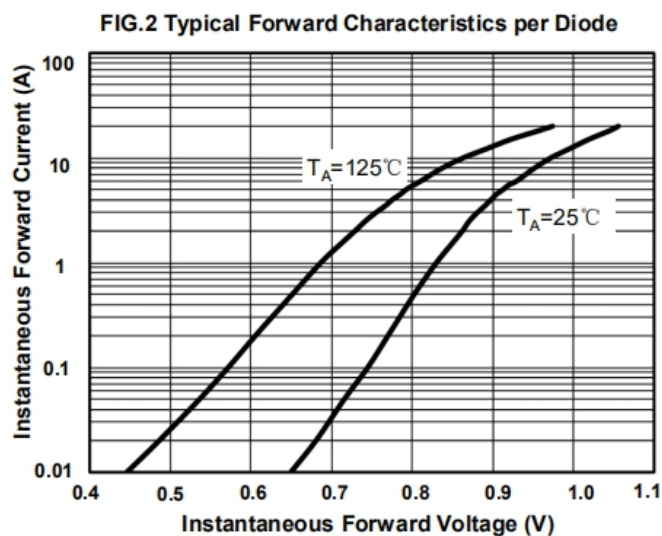
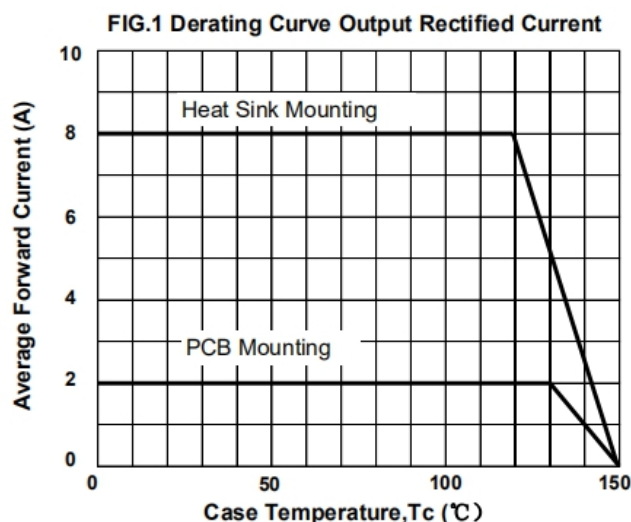


FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode

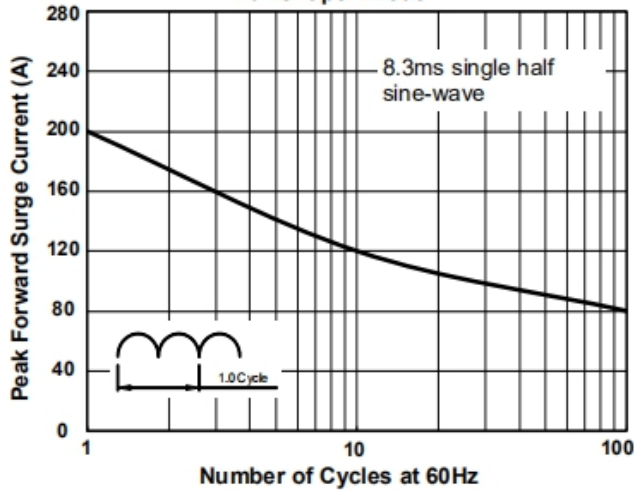


FIG.4 Typical Reverse Characteristics per Diode

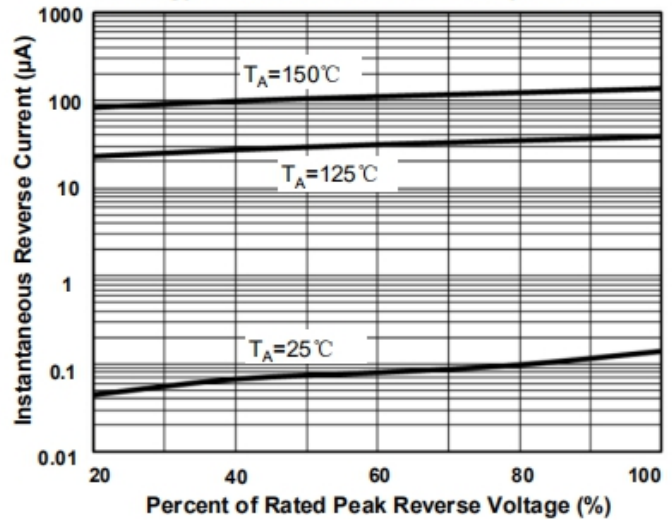
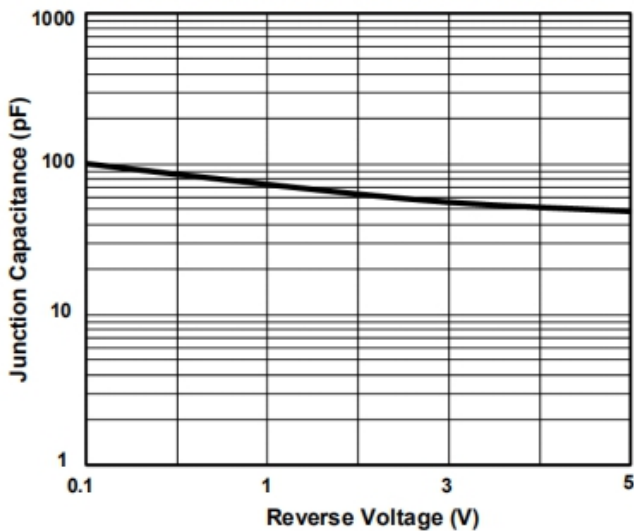
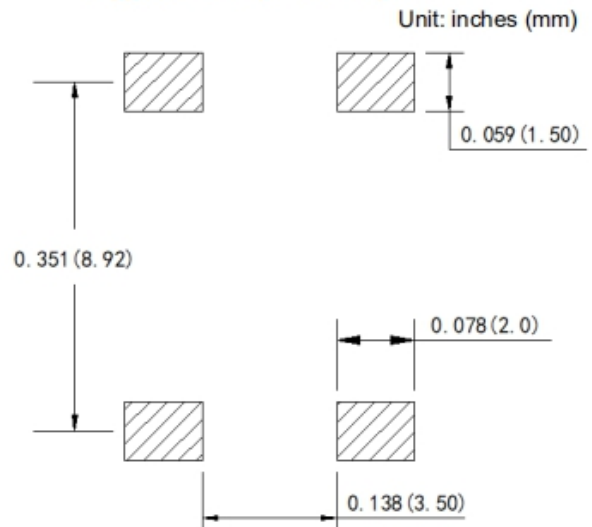


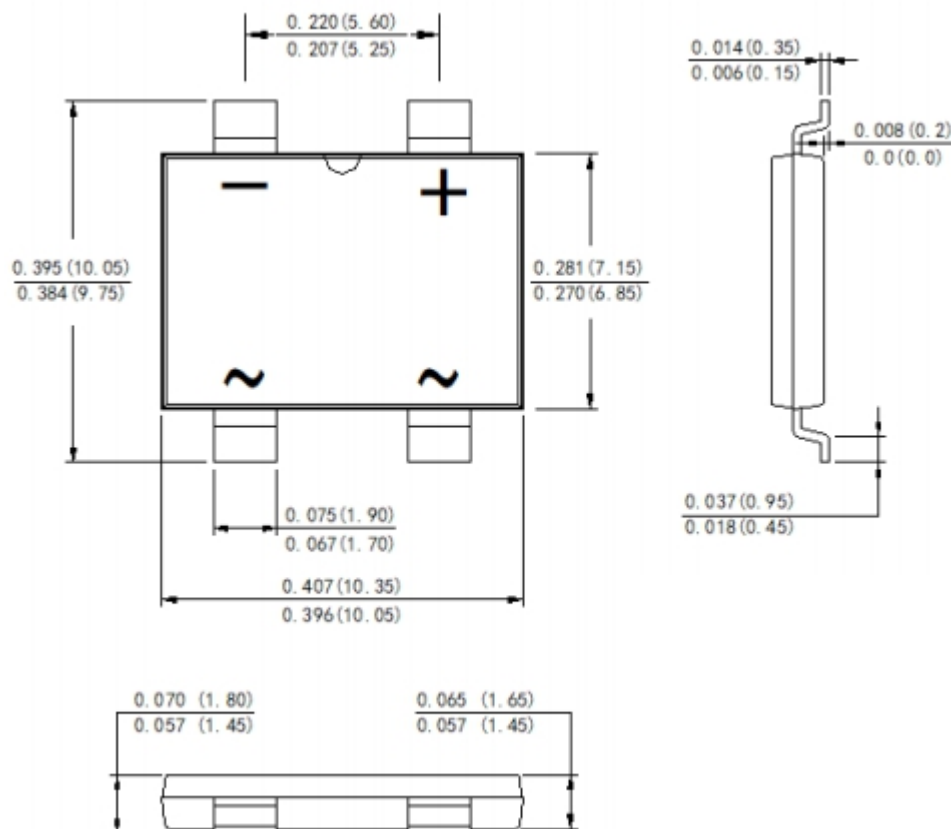
FIG.5 Typical Junction Capacitance per Diode



Suggested PCB printfoot layout



Mechanical Dimensions HBS(Inches/Millimeters)



Ordering Information

Device	Package	Plating	Shipping
HBS802 THRU HBS810	HBS (Pb-Free)	Pure Sn	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

HBS802 = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

**Technical Data
Data Sheet N2257, Rev. -**



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